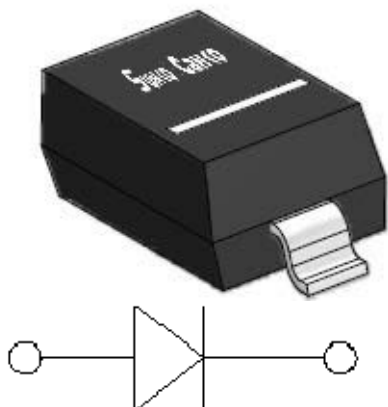


Small Signal Schottky Diode



Features

- V_R 100V
- I_{FAV} 150mA

Mechanical Data

- **Package:** SOD-323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end
- **Marking:** S9

■Maximum Ratings ($T_A=25^{\circ}\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Repetitive peak reverse voltage	V_{RRM}	V		100
Non-Repetitive Peak Forward Surge Current	I_{FSM}	mA	$t_p=8.3\text{ms}$	750
Average forward current	I_{FAV}	mA		150
Power dissipation	P_D	mW		200
Thermal Resistance From Junction To Ambient	R_{thJA}	$^{\circ}\text{C}/\text{W}$		625
Junction temperature	T_j	$^{\circ}\text{C}$		125
Storage temperature range	T_{stg}	$^{\circ}\text{C}$		-55 to +150

■Electrical Characteristics ($T_A=25^{\circ}\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Maximum Forward voltage	V_F	V	$I_F=0.1\text{mA}$	0.25
		V	$I_F=10\text{mA}$	0.45
		V	$I_F=250\text{mA}$	1
Maximum Reverse current	I_R	μA	$V_R=1.5\text{V}$	0.3
		μA	$V_R=10\text{V}$	0.5
		μA	$V_R=50\text{V}$	1
		μA	$V_R=75\text{V}$	2
Minimum Breakdown voltage	V_R	V	$I_R=100\mu\text{A}$	100
Maximum Diode capacitance	C_D	pF	$V_R=0\text{V}, f=1\text{MHz}$	20
			$V_R=1\text{V}, f=1\text{MHz}$	12

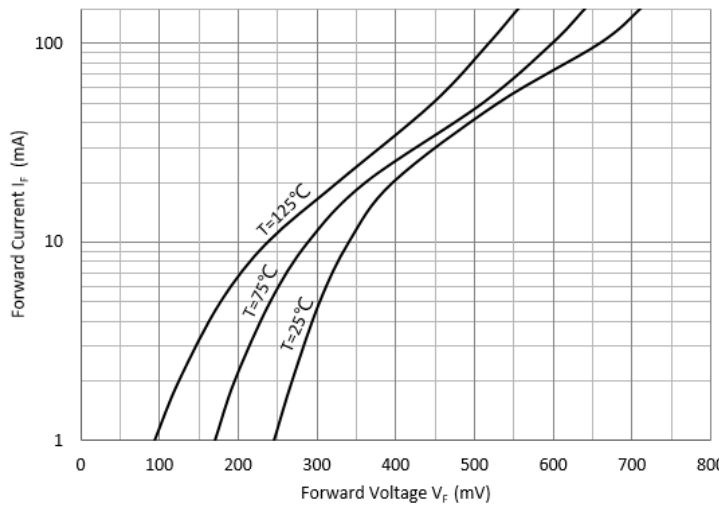
BAT46WS

■ Ordering Information (Example)

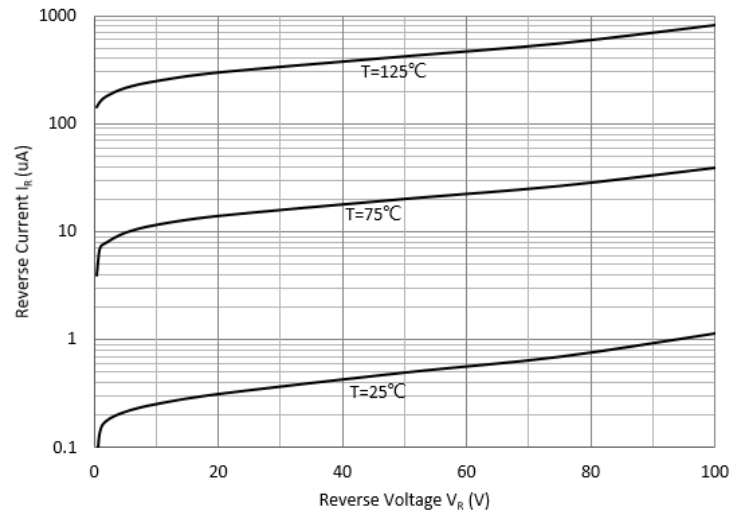
PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
BAT46WS	F2	Approximate 0.0048	3000	30000	120000	7" reel

■ Characteristics (Typical)

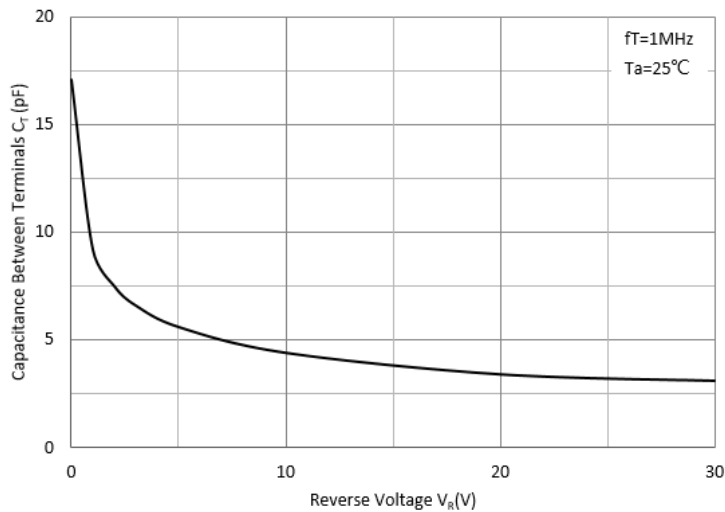
Forward Characteristics



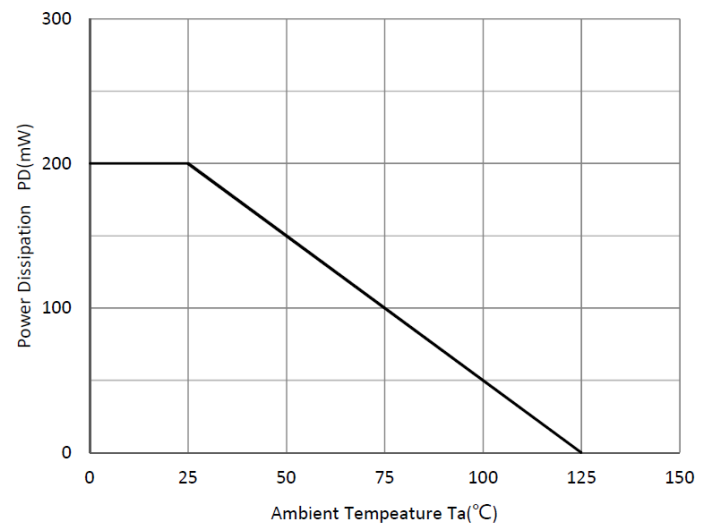
Reverse Characteristics



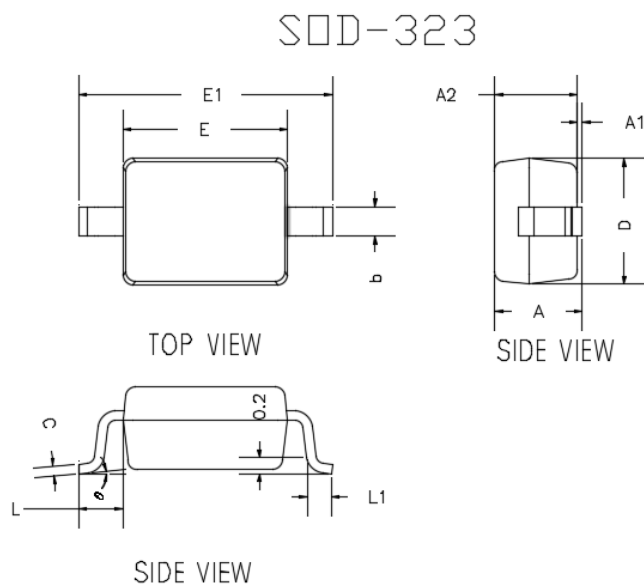
Capacitance Characteristics



Power Derating Curve

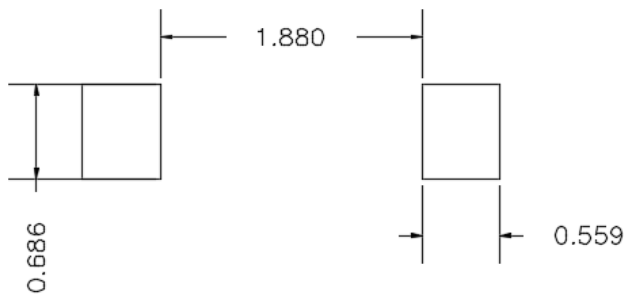


■Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

■Soldering Footprint



UNIT : mm

SUGGESTED SOLDER PAD LAYOUT

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